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ZigBee PRO modules

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Digi International has released new low-power XBee ZB and extended range XBee-PRO ZB ZigBee modules based upon the ZigBee PRO feature set. The ZigBee PRO feature set enables deployment of larger, more stable and interoperable ZigBee networks with advanced features.

The ZigBee PRO feature set provides significant advances in interoperability, node density management, data load management and frequency agility, and builds upon the mesh networking and low-power capabilities of prior feature sets. Based on the Ember EM 250 chip and ZNet 3.1 stack, the new modules are also capable of over-the-air firmware updates, allowing customers to change settings and features without directly accessing hardware.

As a member of the XBee family, the XBee ZB and XBee-PRO ZB modules share a common electrical interface, form factor, and software interface with other XBee platforms, including 802.15.4, ZNet 2.5, and 900 MHz XSC, allowing OEMs to change platforms as needed. As a member of Digi's Drop-in Networking product offering, the new modules will plug into products such as gateways that provide XBee to Ethernet, Wi-Fi and cellular functionality; adapters that provide serial, analog I/O, and digital I/O to XBee functionality; and wall routers that provide network extension functionality.